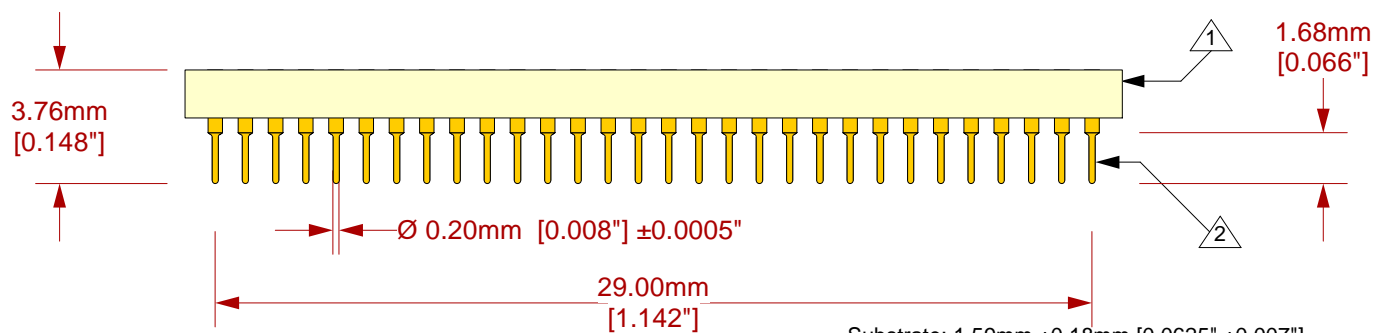


**Side View**



1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]  
FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket

900 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 30x30 array)

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	<b>LS-BGA900A-41 Drawing</b>	Status: Released	Scale: 4:1	Rev: B
	© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: S.Natarajan	Date: 3/4/05	
File: LS-BGA900A-41 Dwg				